

Class	Subc
ISSUE CLASSIFICATION	

U.S. **UTILITY** Patent Application

FILED <i>mw</i> <i>M 1/2</i> O.I.P.E. <i>NS</i> SCANNED <i>IK4</i> Q.A. <i>SW</i>	PATENT DATE
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APPLICATION NO. 09/967094	CONT/PRIOR	CLASS 257	SUBCLASS 774	ART UNIT 2811 2826	EXAMINER F. [unclear]
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APPLICANTS

TITLE

Barrier layer for interconnect structures of a semiconductor wafer and method for depositing the barrier layer

PTO-2040
12/99

ISSUING CLASSIFICATION								
ORIGINAL				CROSS REFERENCE(S)				
CLASS	SUBCLASS			CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)			
INTERNATIONAL CLASSIFICATION								

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	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
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